Advanced Echem Materials Company Ltd.
(Stock code：4749)
Investor Conference

November 17, 2025

Safe Harbor Notice

4749

- AEMC's statements of its current expectations are forward-looking statements subject to significant risks and uncertainties and actual results may differ materially from those contained in the forward-looking statements.
- AEMC makes no representation or warranty regarding such forward-looking statements. Except as required by law, AEMC undertakes no obligation to update any forward-looking statements, whether as a result of new information, future events, or otherwise.

Agenda

4749

- Company Overview
- Main Products and Markets
- Product Roadmap
- ESG Performance
- Appendix

Mission

Establish upstream and downstream supply chains

Our mission is to establish Taiwan's independent technology in specialty chemicals for advanced semiconductor processes and through collaboration, enhance the global competitiveness of the local specialized materials industry, both upstream and downstream.

Vision

Expand the variety of lithography materials and increase market share

Our vision is to enhance Synthesis, Purification, Formulation, and process technologies to meet customer needs, assist in yield improvement deliver exceptional added value, and become an innovative specialty chemical company with global competitiveness.

Paid-in Capital
NT$926M / US$30.8M

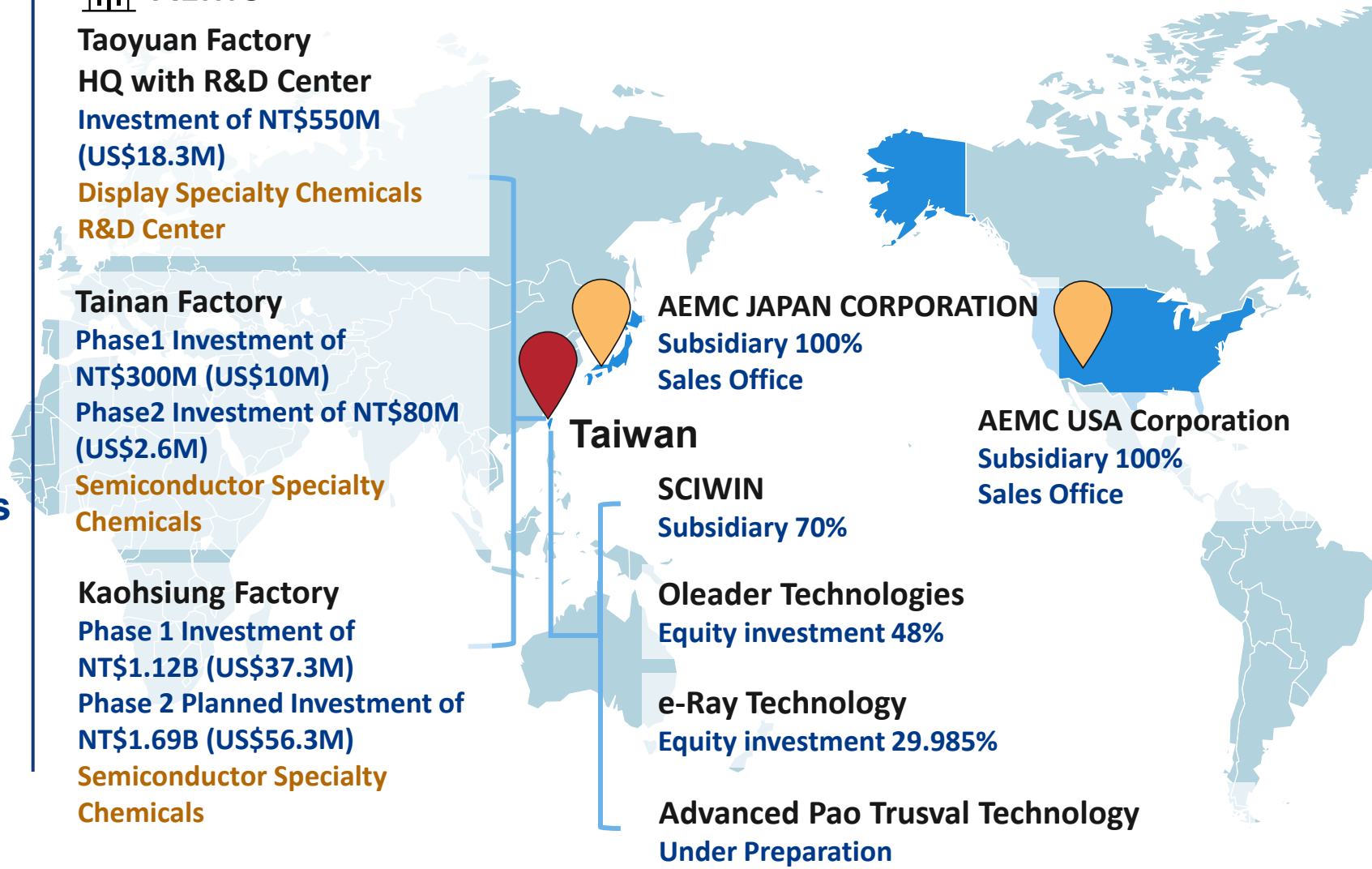
Main Products
- Specialty Materials for Semiconductors
  - Advanced Process Materials
  - Advanced Packaging Materials
  - Optical Component Materials
- Specialty Materials for Displays
  - LCD Photoresist
  - Micro-LED Photoresist

Number of Employees
445 (2025.10)
R&D Personnel:130 (2025.10)

AEMC
Taoyuan Factory
HQ with R&D Center
Investment of NT$550M (US$18.3M)
Display Specialty Chemicals
R&D Center

Tainan Factory
Phase1 Investment of NT$300M (US$10M)
Phase2 Investment of NT$80M (US$2.6M)
Semiconductor Specialty Chemicals

Kaohsiung Factory
Phase 1 Investment of NT$1.12B (US$37.3M)
Phase 2 Planned Investment of NT$1.69B (US$56.3M)
Semiconductor Specialty Chemicals



AEMC JAPAN CORPORATION
Subsidiary 100%
Sales Office

Taiwan

AEMC USA Corporation
Subsidiary 100%
Sales Office

SCIWIN
Subsidiary 70%

Oleader Technologies
Equity investment 48%

e-Ray Technology
Equity investment 29.985%

Advanced Pao Trusval Technology
Under Preparation

Development History and Key Milestones

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AEMC Established

2003

2003-2012 Photoresist for Display Panels

TFT-LCD Array PR & Cleaner
TFT-LCD CF PR & Cleaner
PM-OLED PR
LED PR

Materials for Semiconductor Optical Components

CIS photoresist introduced to semiconductor optical component customers
Retina Material (iphone4)

2014

2018 Semiconductor Specialty Chemicals

Semiconductor i-Line High Rs. PR

Materials for Advanced Semiconductor Processes

Semiconductor Advanced Package PR Production
Semiconductor Advanced Litho Material introduced into Foundry Customer

2020

2022 Advanced Lithography Materials Introduced to Foundry Customer

Rinse/Cleaner-N3,N2
BARC/EBR-N2

Photoresist for Advanced Semiconductor Processes

DUV Photoresist for Advanced Semiconductor Processes

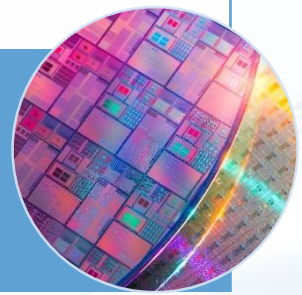
2025

1.4nm、1.0nm

Transformation into Semiconductor Specialty Chemicals

- **Advanced Lithography Process**
  - Rinse
  - EBR
  - Cleaner
  - Developer
  - BARC
- **Advanced Packaging**
- **Optical Component**
  - Image Sensor Material
  - Micro-Optical Component Material

Semiconductor Specialty Chemicals

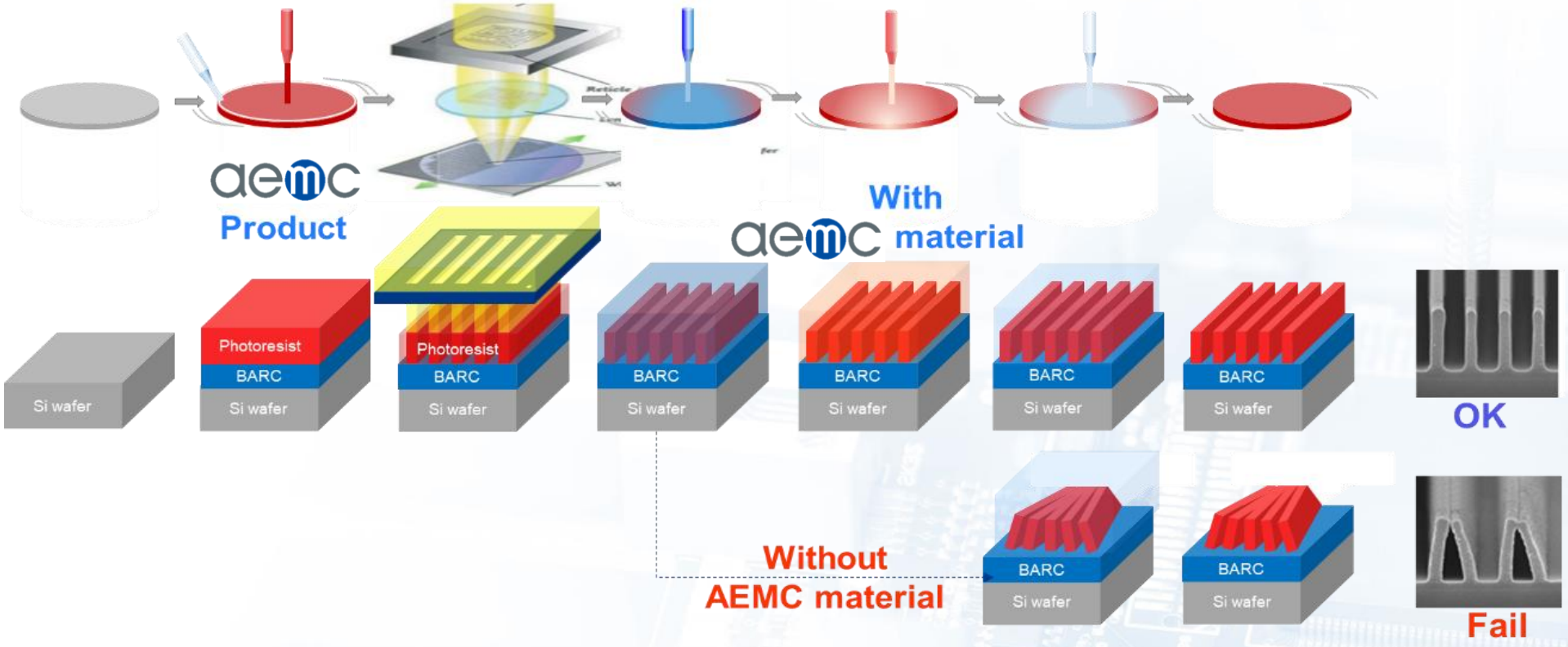


- **TFT LCD**
  - TFT Photoresist
- **Micro LED**
  - QD Ink/PR
  - Gray/White Block Layer PR
  - Release Layer PR
  - Bottom Fill Gel
  - Low-Temperature PR
  - High/Low Refractive Index Materials

Display Specialty Chemicals

Products

- BARC
- EBR
- Developer
- Rinse Material
- Cleaner (Pipeline and Equipment)



Semiconductor Specialty Chemicals- Key Material for Advanced Semiconductor (Rinse)

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Benefits

√ Straightforward process

√ Pattern collapse mitigation

√ Defect reduction

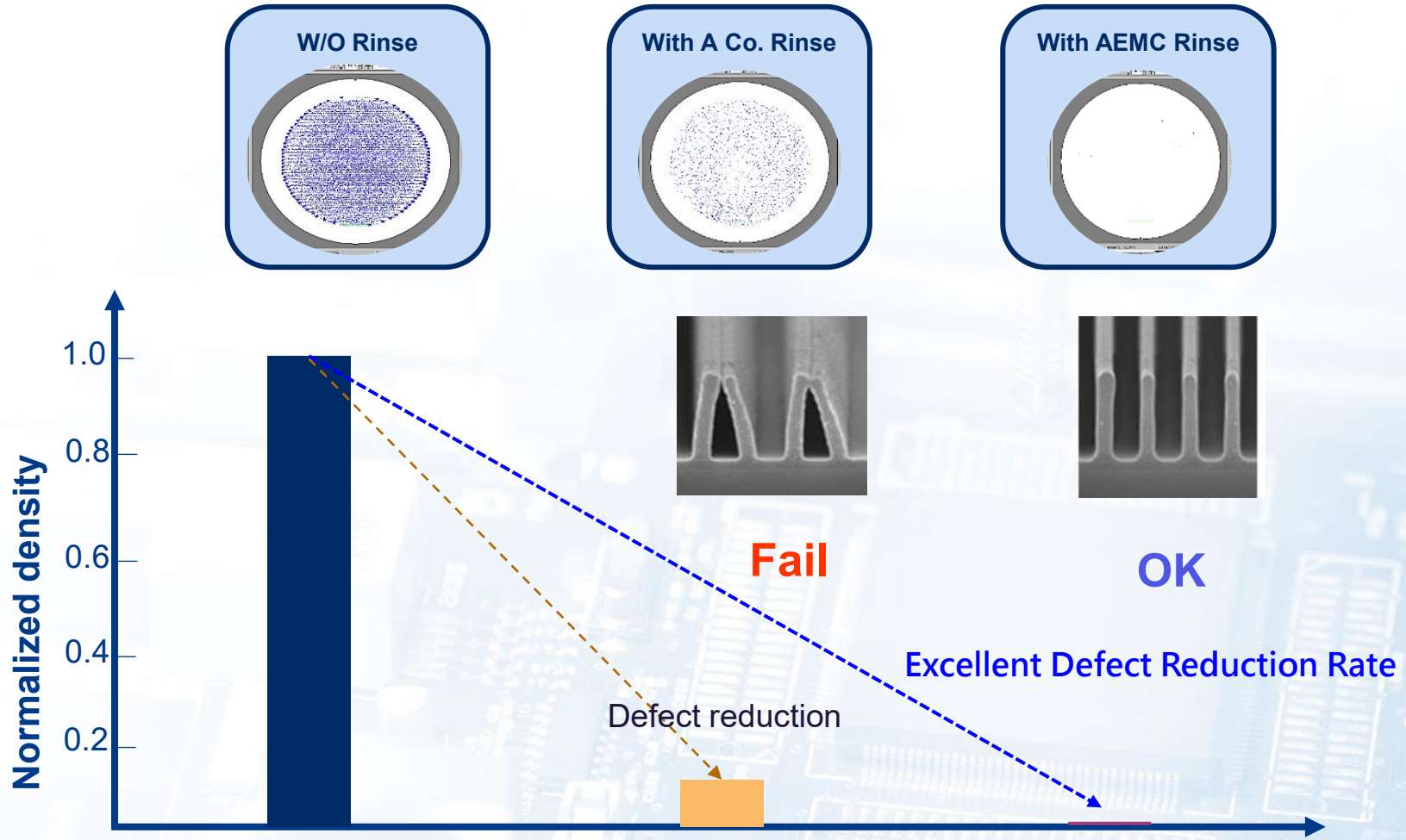
Infusing Professional Resources to Enhance Supplier's R&D Capabilities

Lithography is a critical process in semiconductor manufacturing and is one of the core technologies that ensures chip quality and stability. Due to the high threshold for material research and production technology, the Lithography process has traditionally relied on imported materials. In 2019, in order to enhance the research and development capabilities and production efficiency of the domestic supply chain, TSMC's Material Supply Chain Management (MSCM) collaborated extensively with the Nano Patterning Technology Division (NPTD) to launch the 'Supplier Raw Material Technology Guidance Program'. Offering expert guidance on the seven major aspects of Lithography process materials, including technology development, quality assurance analysis, data calibration, sample verification, factory configuration, tank optimization, and production expansion planning. The program has not only effectively reduced the supplier's line setup and product verification time by 50%, but its material quality also surpasses TSMC's process standards, further improving yield rates and strengthening the competitiveness of the supplier in all aspects. This initiative has laid a solid foundation for the development of the domestic Lithography process material supply chain.

Source: Foundry Customers' ESG Website
https://esg.tsmc.com/zh-Hant/articles/74

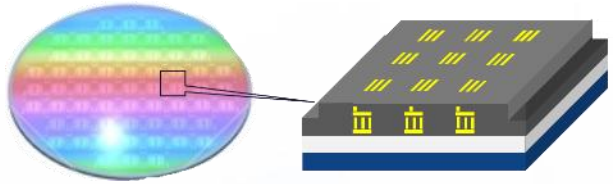
Defect comparison

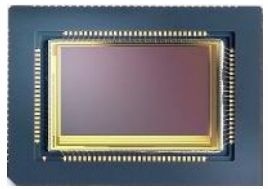
The performance of AEMC's Rinse materials ranks No. 1 in the world.



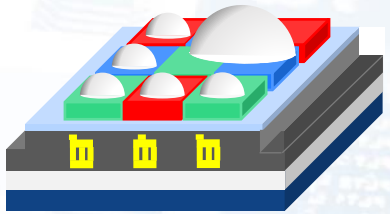
AEMC Product

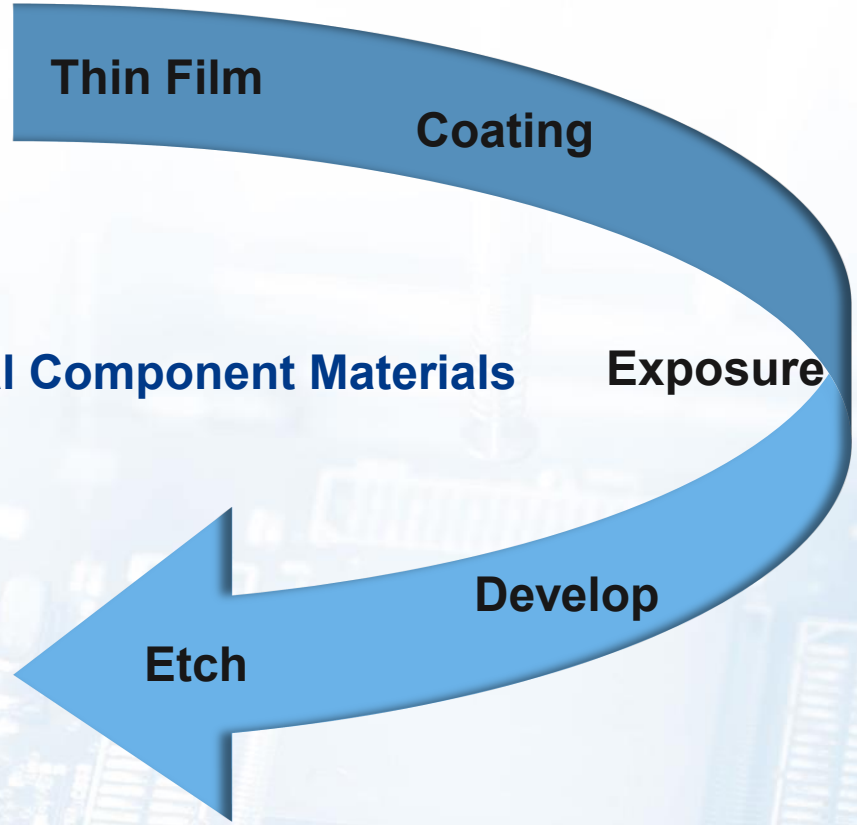
- √ Over Coat PR
- √ Adhesive Promoter
- √ Photo Resist
- √ Micro lens PR
- √ Micro lens Protection PR





CMOS chip



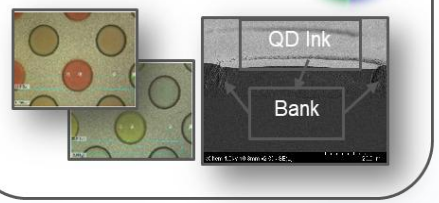


Display Specialty Chemicals

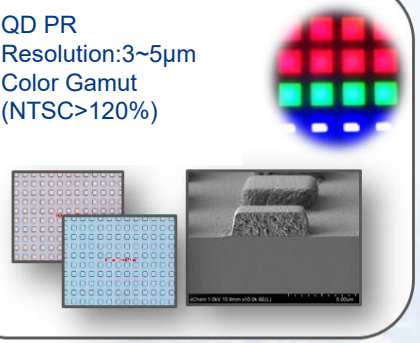
TFT-LCD PR Materials

- TFT LCD PR

QD Ink
Resolution:30~50μm
Color Gamut
(NTSC>120%)



QD PR
Resolution:3~5μm
Color Gamut
(NTSC>120%)

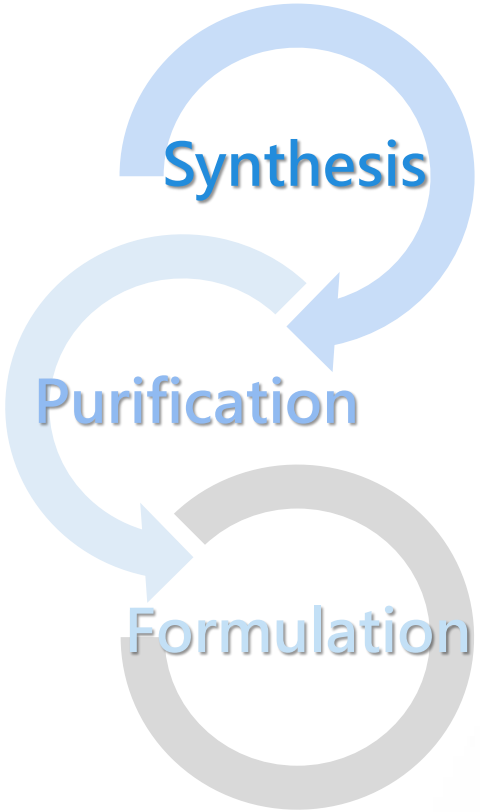


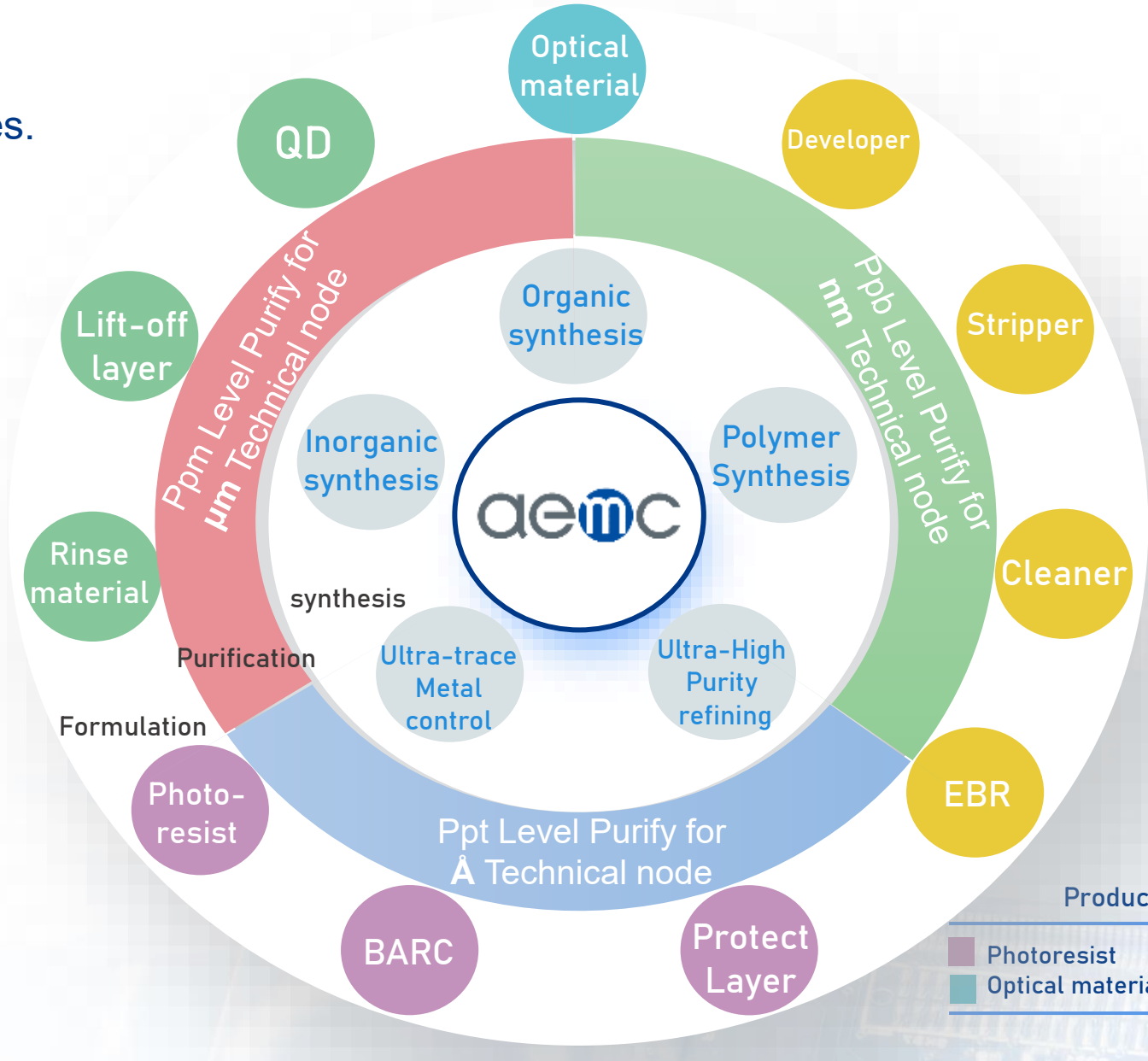
Micro LED QD Key Materials

- QD Ink/PR
- Gray/White Block Layer PR
- Release Layer PR
- Bottom Fill Gel
- Low-Temperature PR
- High/Low Refractive Index Materials

1. Integrating Upstream From Formulation Technology

20 Years of Materials and
>1,000 Formulations Databases.





2: Establishing the Strategic Alliance for TW Material Supply Chain

Existing materials

Mainly relying on external purchases

Monomer/Precursor Synthesis

Self-synthesis or outsourcing(CDMO)

Domestic Universities and Research Institutions

aemc

Standard product

- Display： TFT-LCD

Customized

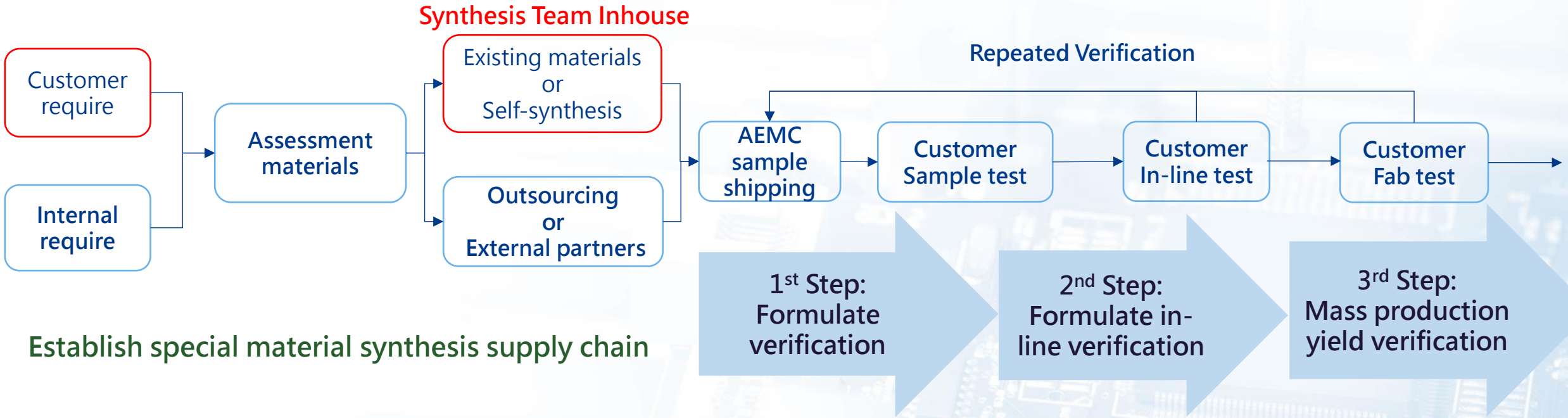
- Semiconductor：Advance Litho-process/Advance package process
- Semiconductor：Optical device
- Display：Micro LED

Higher response speed / Sample delivery frequency

Customized development

Raw material Synthesis

Purification and Formulation



Establish special material synthesis supply chain

6 ~ 18 months

18 ~ 36 months

Excellent Quality Control

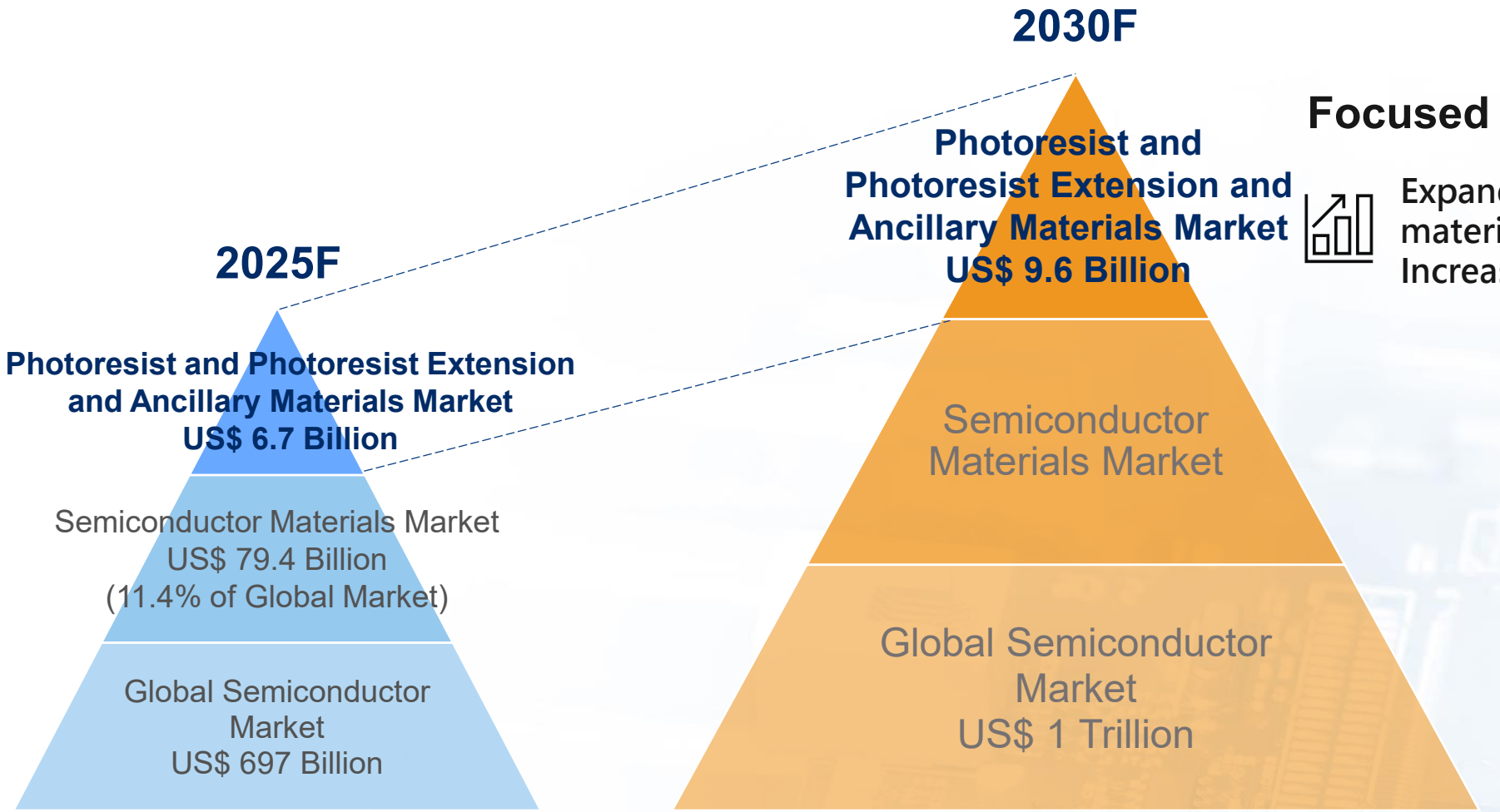
✓ **Quality Control Equipment and Systems:**

1. Building Equipment of the Same Level as Customers
2. Ultra-Trace Impurity Control to Meet the Requirements of Advanced Semiconductor Processes: Evolving from ppb (10^{-9}) to ppt (10^{-12}) levels
3. Intelligent Quality Monitoring System: Automated Product Inspection and Integrated Quality Data Analysis

Self Designed Manufacturing Technology

	Sample Shipping	Trial Production	Mass Production
Product			
In-house Production Line	R&D Lab	Mini line	High Volume Manufacturing

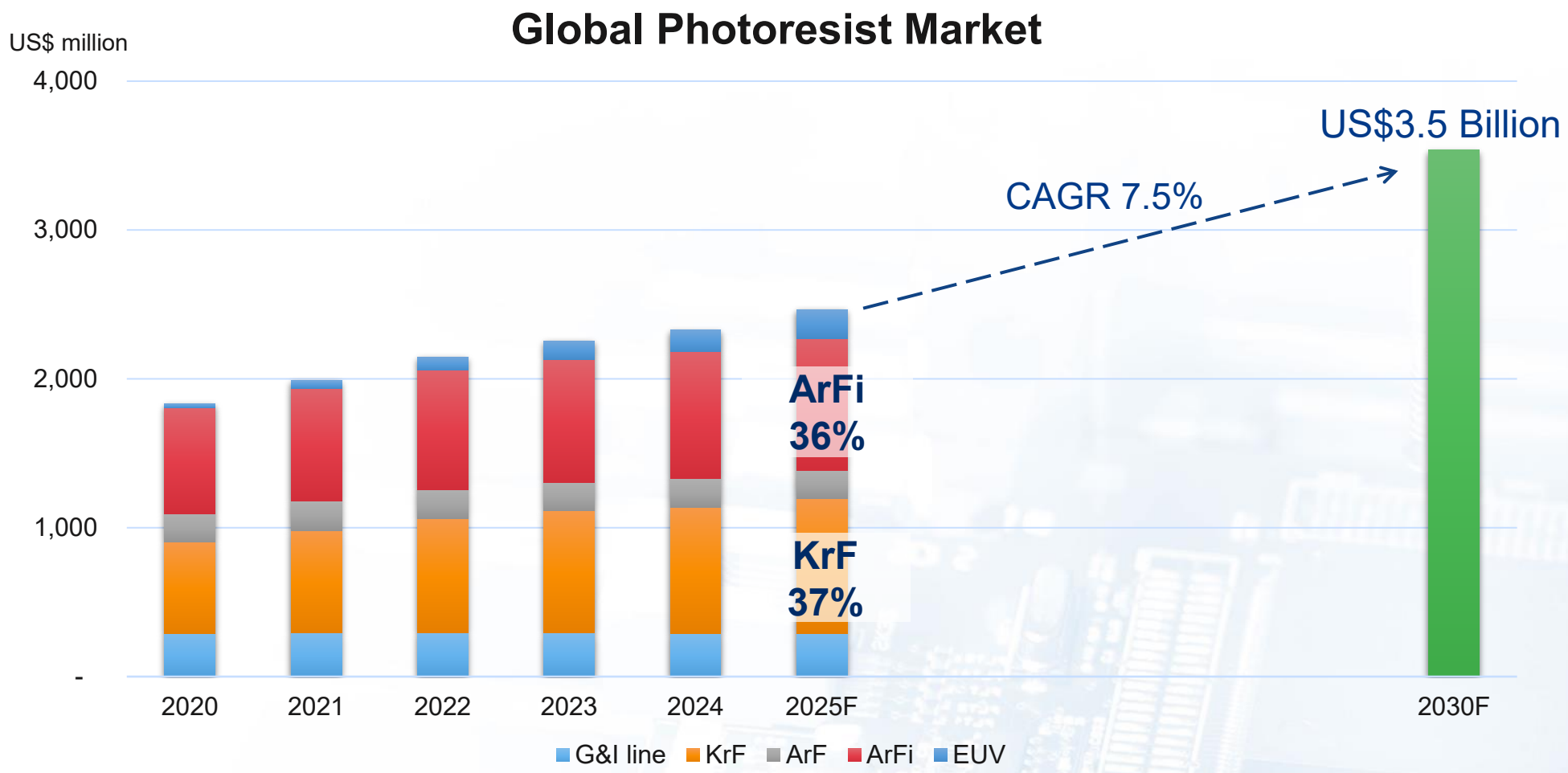
Lithography Materials Market



Focused Market of aemc

- Expand the variety of lithography materials
- Increase market share

Sources：TECHCET(2021)、WSTS(2024)、Deloitte(2025)、 Estimate by AEMC



Sources：TECHCET(2021)、WSTS(2024)、Deloitte(2025)、 Estimate by AEMC

Major Customer’s Advanced Process Capacity Roadmap

Baoshan, Hsinchu
2 fabs / 4 fabs*

Taichung
1 fab / 4 fabs *

Shalun, Tainan
0 fab / 3 fabs *

Kaohsiung
3 fabs / 6 fabs *

USA

Arizona
4/3/2nm
3 fabs / 6 fabs *

JAPAN

Kumamoto
28/22/16/12/7/6nm
2 fab / 2 fabs *

GERMANY

Dresden
28~12nm Automotive ICs
1 fab / 1 fab *

* Number of wafer fabs under construction / Total number of planned fabs
Source: Economic Daily News, Digitimes, and other media reports.

October 18, 2025 – Economic Daily News

…TSMC's (2330) construction of its advanced 1.4-nanometer fab at the Central Taiwan Science Park (A14 site) has begun! On the 17th, TSMC officially submitted its construction commencement application to the park administration. The new fab is expected to begin mass production in the second half of 2028, with an initial investment estimated at up to USD 49 billion (approximately NT$1.5 trillion), creating 8,000 to 10,000 job opportunities. …

October 16, 2025 – Digitimes

TSMC, through its Japanese subsidiary JASM, is planning to build a second wafer fab in Kumamoto Prefecture, Japan. According to TSMC Chairman Mark Liu's remarks during the earnings call on October 16, construction has already begun. However, the mass production schedule for the second Kumamoto fab will depend on customer demand and market conditions. …

October 7, 2025 – Commercial Times

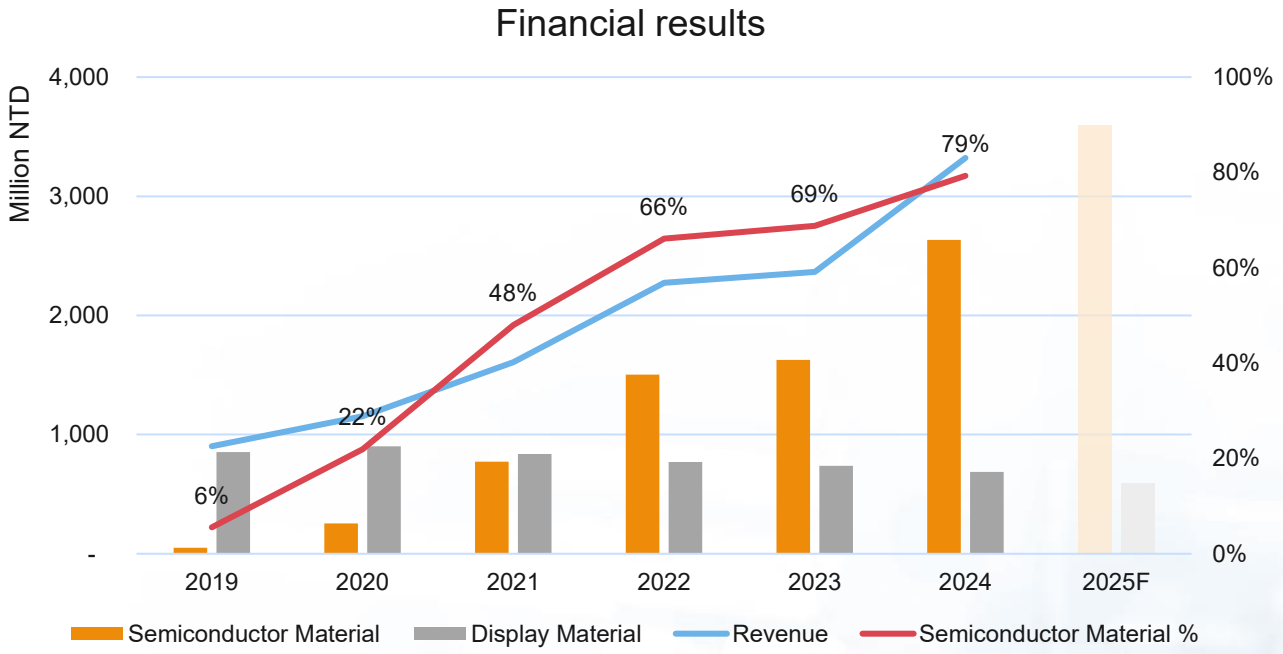
…TSMC's Kaohsiung campus, located on the site of the former CPC refinery and spanning about 170 hectares, represents the largest semiconductor investment in southern Taiwan. It is understood that the P1 fab is confirmed to begin mass production of 2-nanometer wafers by the end of this year. The P2 fab completed equipment move-in in August and is now undergoing installation and calibration, with mass production planned for the second quarter of next year. The P3 fab received construction approval from the Kaohsiung City Government in October last year, while P4 and P5 were approved for construction this July—marking the full activation of all five advanced-process fabs. …

February 3, 2025 – Economic Daily News

…It is understood that TSMC has submitted land-use requests to the Southern Taiwan Science Park for 1.4-nanometer and 1-nanometer fabs in the Shalun area of Tainan. This plan indicates a total of six fabs: the first three (P1–P3) designated for 1.4-nanometer production, and the latter three for 1-nanometer. If the Central Taiwan fab site is successfully delivered and prioritized for 1.4-nanometer production, TSMC's Shalun project may instead allocate the first three fabs to 1-nanometer and the latter three to 0.7-nanometer production. …

Application Field		Mass Production	Verification	Developing
Semiconductor	Advanced Microlithography Materials	• Rinse Material • BARC • EBR • Cleaner	• Rinse Material for next node • BARC for next node • EBR for next node	• DUV Photoresist (KrF) • Bottom Layer • Advanced BARC • Protection Layer
	Advanced Packaging Materials	• NA	• Protection Layer • Cleaner • Photoresist	• Protection Layer • High AR Photoresist • Leveling Layer • Packaging Glue
	Optical Element Materials	• Photoresists • Flat Layer • Color Filter Layer • Light-cut Layer	• Photoresists • Stripper	• DUV Photoresist (ArF) • Leveling Layer • Microlens Materials
Display	Micro-LED Materials	• QD Ink • Bank Layer • Flat Layer	• QD ink • Black Glue	• QD Ink for next generation

Financial Highlights

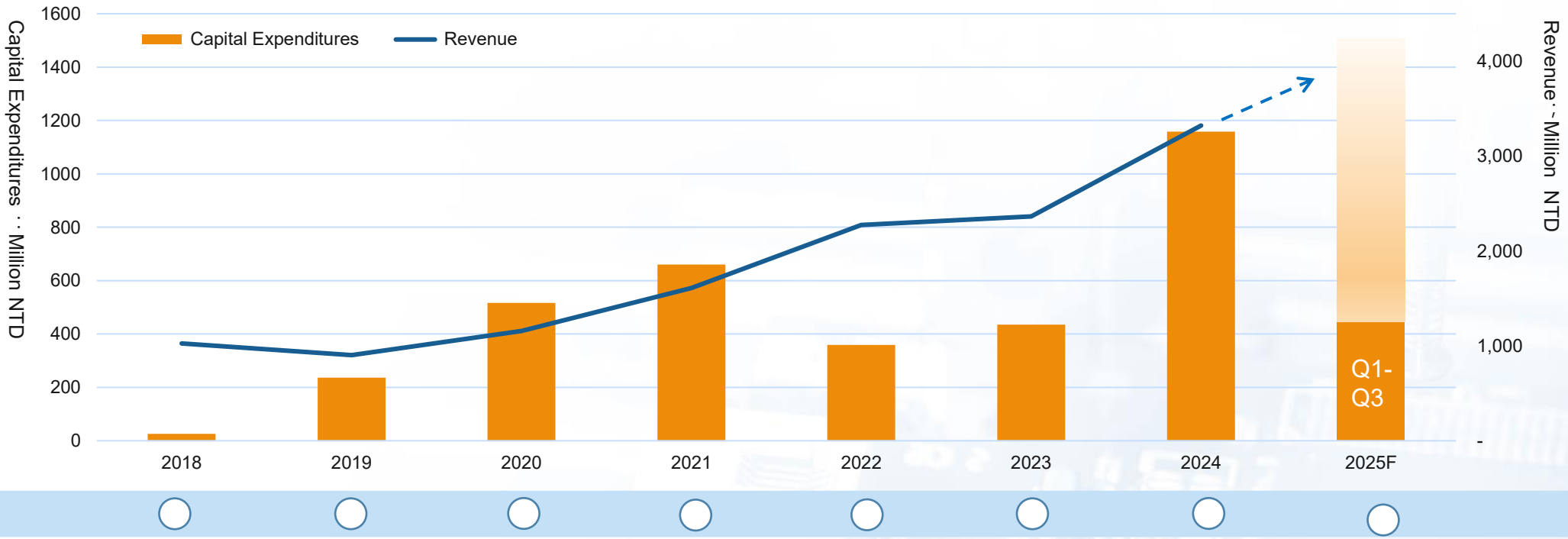


Thousand NTD

年度	2020	2021	2022	2023	2024	1Q2025	2Q2025	3Q2025
Revenue	1,155,590	1,609,310	2,274,422	2,364,382	3,321,861	959,316	1,152,698	1,065,504
Semiconductor Material	253,662	772,820	1,503,477	1,627,118	2,634,121	787,504	1,025,536	938,531
Display Material	901,928	836,490	770,945	737,264	687,740	171,811	127,163	126,973
Gross Profit	297,287	422,167	723,053	694,252	1,204,394	374,655	533,004	450,418
Operating Income	(6,442)	52,685	295,186	224,802	586,794	191,380	357,504	259,148
Pre-tax Net Income	13,277	132,458	465,957	361,436	828,347	249,870	347,192	336,588
Net Income Attributable to the Parent Company	13,277	122,346	403,500	318,372	697,538	207,757	284,603	290,131
EPS	0.21	1.62	5.01	3.91	8.5	2.28	3.07	3.13

Capital Expenditures and Growth Development Trends

Since transitioning to semiconductor material development in 2018, the cumulative capital expenditure as of the end of 2024 has exceeded NT$3.3 billion.



SEMI i-Line High Rs. Photoresist

CIS Lithography Process Special Materials

Rinse and Cleaner for Advanced SEMI Processes

Developer for Advanced SEMI Processes

EBR for Advanced SEMI Lithography Processes

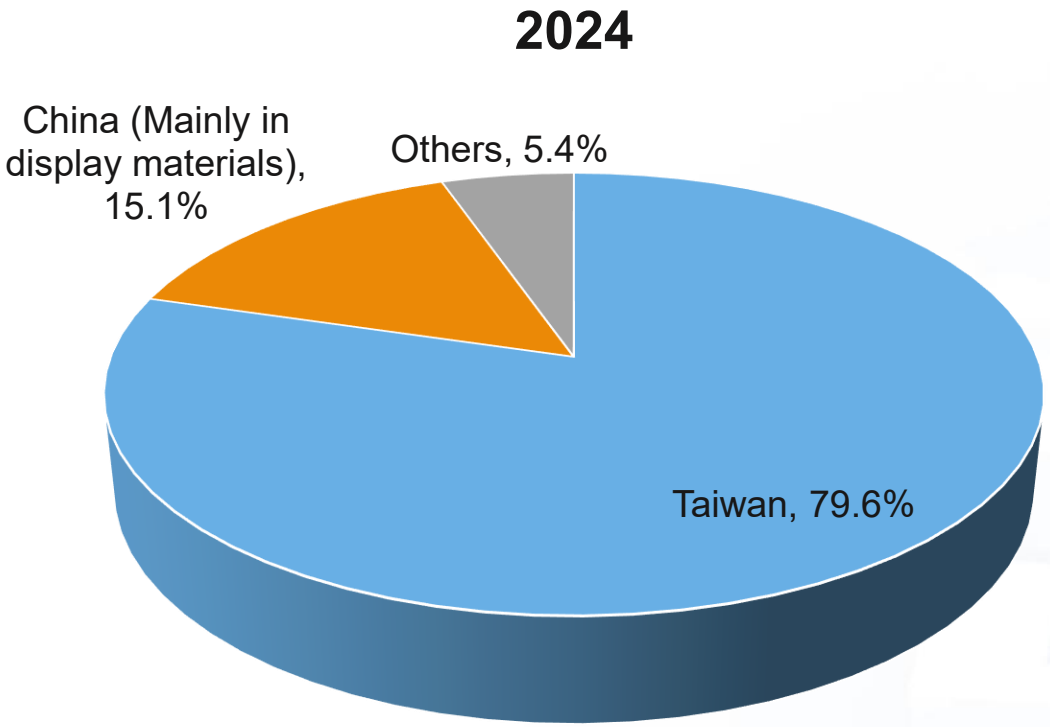
BARC for Advanced SEMI Lithography Processes

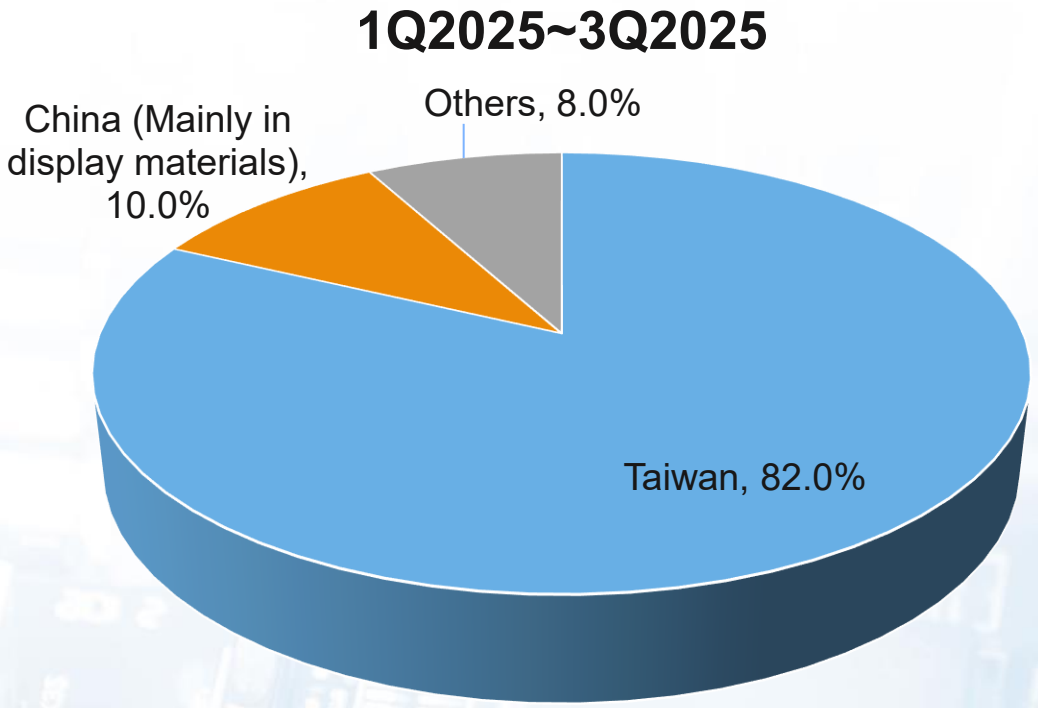
Special Cleaning Solution for Advanced SEMI Lithography Processes

DUV Photoresist for Advanced Semiconductor Processes

Advanced Packaging Materials

Sales Regions





Note: Other sales regions include the United States, Japan, Singapore, and others.

ESG Performance

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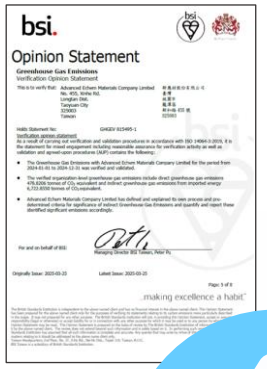
Completed greenhouse gas inventory ahead of regulatory schedule and obtained a statement from a third-party verification body in 2024.

Awarded a certificate of appreciation by a major wafer foundry customer for the 'Supplier Energy Saving and Carbon Reduction Guidance Program'


bsi.

Opinion Statement

Greenhouse Gas Emissions

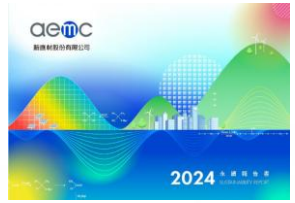
Verification Opinion Statement

making excellence a habit.

4 Independent directors, accounting for more than 44%

2 Female directors, accounting for more than 22%

Sustainability Report to be issued in 2025



Female employees>35%

Female Executives and Managers> 35%

Employees voluntarily organize and participate in ESG activities.

- Established the ‘AEMC Scholarship’
- Founded the 'New Immigrant Children Scholarship’
- Actively participated in 'Industry-Academia Cooperation


Tree Planting Event

Shoe Donation Event

Thank you for listening.

Q&A

Income Statement

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NT$ million	3Q25	2Q25	3Q24	QOQ	YOY
Net Revenue / Net Sales	1,066	1,153	857	-7.6%	24.4%
Gross Profit	450	533	323	-15.5%	39.6%
Gross Margin	**42.3%**	**46.2%**	**37.7%**	**-8.6%**	**12.3%**
Operating Expenses	191	176	157	8.7%	21.8%
Operating Profit	259	358	166	-27.5%	56.1%
Operating Margin	**24.3%**	**31.0%**	**19.4%**	**-21.6%**	**25.5%**
Non-operating Income and Expenses	77	-10	27	-851.8%	183.5%
Net Income Attributable to the Parent Company	290	285	156	1.9%	86.3%
EPS (NT$)	3.13	3.07	1.90	2.0%	64.7%

Balance Sheet

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NT$ million	3Q25		2Q25		3Q24	
	Amount	%	Amount	%	Amount	%
Cash and Cash Equivalents	1,286	12.8%	2,185	21.6%	504	9.9%
Accounts Receivable	552	5.5%	523	5.2%	484	9.5%
Property, Plant and Equipment	3,120	31.0%	3,017	29.8%	2,497	48.9%
Total Assets	10,071	100.0%	10,123	100.0%	5,107	100.0%
Current Liabilities	1,018	10.1%	1,367	13.5%	1,158	22.7%
Long-term Borrowings	-	0.0%	-	0.0%	1,036	20.3%
Total Liabilities	1,172	11.6%	1,525	15.1%	2,339	45.8%
Total Shareholders' Equity	8,899	88.4%	8,588	84.8%	2,768	54.2%
Key Financial Ratios						
Current Ratio	606%		451%		168%	
Debt Ratio	12%		15%		46%	
Net Asset Value Per Share(NT$)	95.96		92.61		33.69	

Cash Flow Statement

NT$ million	3Q25	2Q25	3Q24
Beginning Cash Balance	2,569	2,769	477
Cash Flows from Operating Activities	158	450	283
Depreciation and Amortization Expenses	224	63	59
Capital Expenditures	(116)	(128)	(362)
Long-term Borrowings	(974)	(376)	204
Ending Cash Balance	1,778	2,569	505
Free Cash Flow	43	322	(78)

Note: Free Cash Flow = Cash Flows from Operating Activities – Capital Expenditures